



# Product Change Notification

## 107537 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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# Product Change Notification

**Change Notification #:** 107537 - 00  
**Change Title:** Intel® Core™2 Extreme Processor QX6800, PCN 107537-00, Product Design, B-3 step to G-0 Stepping Conversion  
**Date of Publication:** May 09, 2007

## Key Characteristics of the Change:

Product Design

## Forecasted Key Milestones:

<b>Date of Samples Availability:</b>	May 11, 2007
<b>Date of Qualification Data Availability:</b>	Jul 13, 2007
<b>Date Customer Must be Ready to Receive Post-Conversion Material:</b>	Aug 10, 2007
<b>Date of First Availability of Post-Conversion Material:</b>	Jul 16, 2007

*The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.*

## Description of Change to the Customer:

The Intel® Core™2 Extreme processor QX6800 will undergo the following changes for the B-3 to G-0 processor stepping conversion:

- CPUID will change from 06F7 to 06FB
- New S-specs for converting product
- The Electrical and Mechanical Specifications remain within the current specifications. Intel anticipates no changes to customer platforms designed to previous Intel guidelines.
- Thermal specification has changed: Maximum allowed Case Temperature for the Intel® Core™2 Extreme Quad processor QX6800 on G-0 stepping has been increased by 9.7 °C. Tcontrol offset will remain same relative to 0 with increase in Maximum allowed Case Temperature, which will help reduce acoustics.
  - Psi\_ca\* for the thermal solution has changed from 0.129 °C/W on B-3 stepping to 0.196 C/W on G-0 stepping.

\* Psi\_ca is the Case-to-ambient thermal characterization parameter (psi). It is a measure of thermal solution performance using total package power. Defined as  $(TC - TA) / \text{Total Package Power}$ .

## Customer Impact of Change and Recommended Action:

Minimal re-qualification and/or validation is expected for the G-0 stepping conversion due to no feature set changes between the B-3 and G-0 steppings. Thermal qualification may be required, if new thermal solution is implemented to take advantage of this Maximum allowed Case Temperature change. The Intel® Core™2 Extreme desktop processors QX6800 G-0 stepping will require a BIOS update.

- Refer to Intel® Core™2 Extreme Quad-Core Processor QX6000 Sequence and Intel® Core™2 Quad Processor Q6000 Sequence Electrical, Mechanical, and Thermal Specifications (EMTS)

## Products Affected / Intel Ordering Codes:

Processor#	Frequency	Pre Conversion Product Code	Pre Conversion S-Spec	Pre Conversion MM#	Post Conversion Qualification Samples QDF#	Post Conversion Qualification Samples MM#	Post Conversion Product Code	Post Conversion S-Spec	Post Conversion MM#
QX6800	2.93 GHz	HH80562PH0778M	S L9UK	885490	QXWX	890917	HH80562XH0778M	SLACP	891045

## Reference Documents / Attachments:

Document:

Location #:

## PCN Revision History:

Date of Revision:

May 9, 2007

Revision Number:

00

Reason:

Originally Published PCN